Appendix 3 Product End-of-Life Disassembly instructions

Product Identification:

<table>
<thead>
<tr>
<th>Model Name</th>
<th>HP Pavilion m7000 Series PC</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description</td>
<td>Desktop PC</td>
</tr>
</tbody>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product.</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 square cm</td>
<td>6</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 square cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB / PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td>Declaration limited to case plastics only.</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
containing refractory ceramic fibers

| Components, parts and materials containing radioactive substances | 0 |

### 2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Clipper</td>
<td></td>
</tr>
<tr>
<td>Screw Driver</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

<table>
<thead>
<tr>
<th>Step</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>Side Panel Access Disassemble: loosening two thumb screws, removing side panel access</td>
</tr>
<tr>
<td>2</td>
<td>Main Bezel Disassemble: ejecting three hooks, opening main bezel</td>
</tr>
<tr>
<td>3</td>
<td>HDD Storage Holder Disassemble: pull snap up, pull HDD Storage Holder out, turn the screws to loosen it, take HDD Storage Holder out of Chassis</td>
</tr>
<tr>
<td>4</td>
<td>HDD Disassemble: pull HDD out of HDD Storage Holder</td>
</tr>
<tr>
<td>5</td>
<td>HDD Bay Disassemble: turn the screws(*4) to loosen it, take HDD Bay out of HDD Storage Holder</td>
</tr>
<tr>
<td>6</td>
<td>HDD Bay bezel Disassemble: pull HDD Bay bezel out</td>
</tr>
<tr>
<td>7</td>
<td>HDD Bay door Disassemble: take away the both side spring, take HDD Bay door out</td>
</tr>
<tr>
<td>8</td>
<td>HDD Bay connector Disassemble: turn the screws(*2) to loosen it, take it out of HDD Bay</td>
</tr>
<tr>
<td>9</td>
<td>ODD Disassemble: pull snap up, turn the screws(*4) to loosen it, take ODD out of Chassis</td>
</tr>
<tr>
<td>10</td>
<td>ODD_HDD latch Disassemble: press hook, pull snap up, take ODD_HDD latch out</td>
</tr>
<tr>
<td>11</td>
<td>Power Supply Disassemble: turn the screws(*4) to loosen it, take Power Supply out of Chassis</td>
</tr>
<tr>
<td>12</td>
<td>M/B Disassemble: turn the screws(*7) to loosen it, take M/B out of Chassis. <strong>Remove RTC coin cell battery for selective treatment.</strong></td>
</tr>
<tr>
<td>13</td>
<td>EMI Shield Disassemble: pull snap up, take out of I/O shield</td>
</tr>
<tr>
<td>14</td>
<td>Metal Fan Disassemble: turn the screws(*4) to loosen it, take Metal fan out of Chassis</td>
</tr>
<tr>
<td>15</td>
<td>Cable tie Disassemble (includable: Front I/O cables, Power LED cable, cardreader cable, Antenna cable, Magneto cable): loosen the cable tie, pull it out of chassis</td>
</tr>
<tr>
<td>16</td>
<td>Antenna Holder Disassemble: pull snap up and pull Antenna Holder out of Chassis</td>
</tr>
<tr>
<td>17</td>
<td>Antenna Disassemble: pull snap up, take Antenna out of Antenna Holder</td>
</tr>
<tr>
<td>No.</td>
<td>Description</td>
</tr>
<tr>
<td>-----</td>
<td>----------------------------------------------------------------------------------------------</td>
</tr>
<tr>
<td>18</td>
<td>Wireless LED holder Disassemble: press Wireless LED holder both side hook to take it out</td>
</tr>
<tr>
<td>19</td>
<td>Wireless LED Disassemble: pull LED out of Wireless LED holder</td>
</tr>
<tr>
<td>20</td>
<td>Front I/O Disassemble: turn the screw to loosen it, pull the front I/O bezel backward, take</td>
</tr>
<tr>
<td></td>
<td>Front I/O out of cage</td>
</tr>
<tr>
<td>21</td>
<td>Main Bezel Sub-Disassemble Optional parts: Press two hooks to take out of I/O bezel trim up</td>
</tr>
<tr>
<td>22</td>
<td>ODD Label Disassemble: Using a thin slice iron push ODD label out</td>
</tr>
<tr>
<td>23</td>
<td>Nameplate Disassemble: Ejecting two hooks</td>
</tr>
<tr>
<td>24</td>
<td>Wireless Label Disassemble: Press the two hooks inward to lease them, push the horizontal part</td>
</tr>
<tr>
<td></td>
<td>out</td>
</tr>
<tr>
<td>25</td>
<td>Top Mesa-Ferris Disassemble : pull out Top Mesa-Ferris</td>
</tr>
<tr>
<td>26</td>
<td>Top Mesa-kepler Disassemble : pull out Top Mesa-kepler</td>
</tr>
<tr>
<td>27</td>
<td>Top Mesa-ipod Disassemble : pull out Top Mesa-ipod</td>
</tr>
<tr>
<td>28</td>
<td>Power button Disassemble: press two hooks and take out the Power button</td>
</tr>
<tr>
<td>29</td>
<td>Power cosmetic piece Disassemble: pull out Power cosmetic piece</td>
</tr>
<tr>
<td>30</td>
<td>HDD lence Disassemble: loosen HDD lence</td>
</tr>
<tr>
<td>31</td>
<td>Eject ODD button Disassemble: pull out Eject ODD button and using a thin slice iron push</td>
</tr>
<tr>
<td></td>
<td>Eject ODD button Foam out</td>
</tr>
<tr>
<td>32</td>
<td>Spring of Eject ODD button Disassemble: pull the spring out of the hooks</td>
</tr>
<tr>
<td>33</td>
<td>ODD light pipe BR Bar comb Disassemble: turn two screws to loosen it, pull out ODD light pipe</td>
</tr>
<tr>
<td></td>
<td>BR Bar comb</td>
</tr>
<tr>
<td>34</td>
<td>CD shutter button Disassemble: pull out CD shutter button</td>
</tr>
<tr>
<td>35</td>
<td>ODD light pipe Disassemble: press the hooks and take out ODD light pipe</td>
</tr>
<tr>
<td>36</td>
<td>CD shutter top Disassemble: pull out CD shutter top</td>
</tr>
<tr>
<td>37</td>
<td>Front I/O door(including left, right) Disassemble: pull out Front I/O door(including left,</td>
</tr>
<tr>
<td></td>
<td>right)</td>
</tr>
<tr>
<td>38</td>
<td>Sub-Bezel Disassemble: press hooks (*10) step by step, take out Sub-Bezel</td>
</tr>
<tr>
<td>39</td>
<td>Jewel Logo Disassemble: Using a thin slice iron push Jewel Logo out</td>
</tr>
<tr>
<td>40</td>
<td>Top cover Disassemble: pull the top cover backwards and take out the Top cover</td>
</tr>
<tr>
<td>41</td>
<td>Top base Disassemble: press hooks (*10) step by step, take out top base</td>
</tr>
<tr>
<td>42</td>
<td>Top door Disassemble: pull out the top door and fdd bushing</td>
</tr>
<tr>
<td>43</td>
<td>Power switch holder Disassemble: press Power switch holder both side hook to take it out</td>
</tr>
<tr>
<td>44</td>
<td>Power LED Disassemble: take out 2 LED from Power switch holder</td>
</tr>
<tr>
<td>45</td>
<td>Power switch Disassemble: take out power switch from Power switch holder</td>
</tr>
<tr>
<td>46</td>
<td>EN rubber feet Disassemble: Using a thin slice iron push EN rubber feet out</td>
</tr>
</tbody>
</table>
3.2 OPTIONAL: Depending upon the complexity of the disassembly process, a graphic depicting the locations of items contained within the product which require selective treatment (with descriptions and arrows identifying locations) can be inserted below: